SCDS070B - JULY 1998 - REVISED JUNE 2000

- Standard '16245-Type Pinout
- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Latch-Up Performance Exceeds 100 mA Per JESD 78. Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV), and Shrink Small-Outline (DL) Packages

description

The SN74CBT16245 device provides 16 bits of high-speed TTL-compatible bus switching in a standard '16245 device pinout. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as two 8-bit low-impedance switches with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the switch is on, and data can flow from the A port to the B port, or vice versa. When \overline{OE} is high, the switch is open, and a high-impedance state exists between the two ports.

The SN74CBT16245 is characterized for operation from –40°C to 85°C.

DGG, DGV, OR DL PACKAGE (TOP VIEW)

1			
NC [₁ O	48	10E
1B1	2	47] 1A1
1B2	3	46	1A2
GND	4	45	GND
1B3	5	44] 1A3
1B4 🛚	6	43] 1A4
v _{cc} [7	42] v _{cc}
1B5 🛚	8	41	1A5
1B6	9	40	1A6
GND [10	39	GND
1B7	11	38	1A7
1B8	12	37	1A8
2B1	13	36	2A1
2B2	14	35	2A2
GND	15	34	GND
2B3	16	33	2A3
2B4	17	32	2A4
v _{cc} [18	31] v _{cc}
2B5 🛚	19	30	2A5
2B6	20	29	2A6
GND	21	28	GND
2B7	22		2A7
2B8	23	26	2A8
NC [24	25	20E

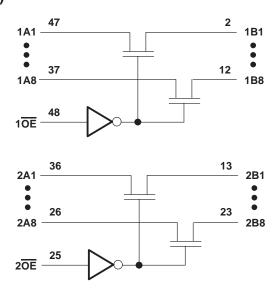
NC - No internal connection

FUNCTION TABLE (each 8-bit bus switch)

INPUT OE	FUNCTION	
L	A port = B port	
Н	Disconnect	

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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		0.5 V to	7 V
Input voltage range, V _I (see Note 1)		0.5 V to	7 V
Continuous channel current			mΑ
Input clamp current, I _{IK} (V _{I/O} < 0)		–50	mΑ
Package thermal impedance, θ _{JA} (see Note 2)	: DGG package	70°C	C/W
	DGV package	58°C	C/W
	DL package	63°C	C/W
Storage temperature range, T _{stg}			0°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	4	5.5	V
VIH	High-level control input voltage	2		V
V _{IL}	Low-level control input voltage		0.8	V
TA	Operating free-air temperature	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PAR	AMETER	TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT		
VIK		$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA				-1.2	V	
II		$V_{CC} = 0$,	V _I = 5.5 V				10	^	
		$V_{CC} = 5.5 \text{ V},$	$V_I = 5.5 \text{ V or GND}$				±1	μΑ	
Icc		$V_{CC} = 5.5 \text{ V},$	I _O = 0,	$V_I = V_{CC}$ or GND			3	μΑ	
∆lcc [‡]	Control inputs	$V_{CC} = 5.5 \text{ V},$	One input at 3.4 V,	Other inputs at V _{CC} or GND			2.5	mA	
Ci	Control inputs	V _I = 3 V or 0				3.5		pF	
C _{io(OFF)}		$V_0 = 3 \text{ V or } 0,$	OE = V _{CC}			4.5		pF	
r _{on} §		$V_{CC} = 4 \text{ V},$ TYP at $V_{CC} = 4 \text{ V}$	V _I = 2.4 V,	I _I = 15 mA		14	20		
			CC = 4.5 V V _I = 0	I _I = 64 mA		5	7	Ω	
		V _{CC} = 4.5 V		I _I = 30 mA		5	7		
			V _I = 2.4 V,	I _I = 15 mA		8	12		

 $^{^{\}dagger}$ All typical values are at V_{CC} = 5 V (unless otherwise noted), T_A = 25°C.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4 V	V _{CC} = 5 V ± 0.5 V		UNIT
	(1141 01)		MIN MAX	MIN	MAX	
t _{pd} ¶	A or B	B or A	0.35		0.25	ns
^t en	ŌĒ	A or B	6.1	1.2	5.6	ns
^t dis	ŌĒ	A or B	7.5	3.9	7.7	ns

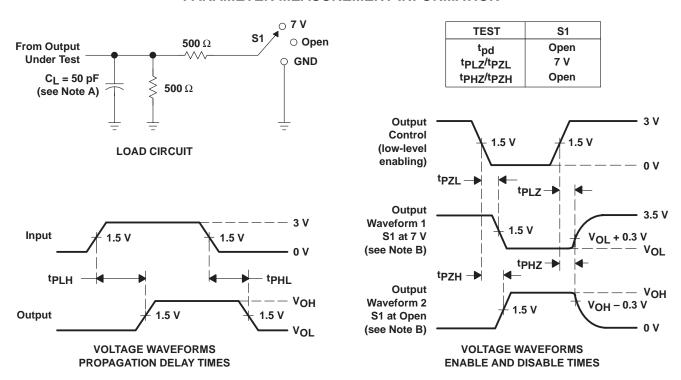
The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).



[‡]This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_f \leq$ 2.5 ns. $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

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